<table>
<thead>
<tr>
<th>BOARD NAME:</th>
<th>BOARD REV:</th>
<th>KSID:</th>
<th>JOB NUMBER:</th>
</tr>
</thead>
<tbody>
<tr>
<td>XXXXXXXXX</td>
<td>A</td>
<td>16940</td>
<td>129285</td>
</tr>
</tbody>
</table>

ALL ARTWORK LAYERS VIEWED FROM TOP

LAYER DESCRIPTION:
SOLDERMASK/BANDS/ARTWORK/BOTTOM
ALL ARTWORK LAYERS VIEWED FROM TOP

TIDA-01090 AUTOMATIC DIRECTION CONTROL RS485
ALL ARTWORK LAYERS VIEWED FROM TOP

BOARD NAME: XXXXXXXX

BOARD REV: A
KSID: 16940
JOB NUMBER: 129285

LAYER DESCRIPTION: XPASIDEMASK XTOPX XXXXX
<table>
<thead>
<tr>
<th>LAYER</th>
<th>DESCRIPTION</th>
<th>TRACING</th>
<th>BOARD FINISH</th>
<th>BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)</th>
</tr>
</thead>
<tbody>
<tr>
<td>L1</td>
<td>COPPER_1/2OZ_PLATED 1.4 MIL</td>
<td>0.017&quot;</td>
<td>SOLDERMASK-0.8MIL 0.8 MIL</td>
<td>MIN. TRACK WIDTH 1/8&quot; &amp; MIN. CLEARANCE 1/32&quot;</td>
</tr>
<tr>
<td>L2</td>
<td>COPPER_1.0OZ 1.4 MIL</td>
<td>0.017&quot;</td>
<td></td>
<td>MIN. ANNULAR 2 MIL EXTERNAL PER IPC-6012C CLASS 2</td>
</tr>
<tr>
<td>L3</td>
<td>COPPER_1.0OZ 1.4 MIL</td>
<td>0.017&quot;</td>
<td></td>
<td>MIN. VEL. FILL USING NON-CONDUCTIVE EPOXY: FILL_0.250 9.84 MIL</td>
</tr>
<tr>
<td>L4</td>
<td>COPPER_1/2OZ_PLATED 1.4 MIL</td>
<td>0.017&quot;</td>
<td></td>
<td>VIA FILL USING NON-CONDUCTIVE EPOXY: FILL_0.250 9.84 MIL</td>
</tr>
<tr>
<td>L5</td>
<td>COPPER_1.0OZ 1.4 MIL</td>
<td>0.017&quot;</td>
<td></td>
<td>VIA FILL USING NON-CONDUCTIVE EPOXY: FILL_0.250 9.84 MIL</td>
</tr>
<tr>
<td>L6</td>
<td>COPPER_1.0OZ 1.4 MIL</td>
<td>0.017&quot;</td>
<td></td>
<td>VIA FILL USING NON-CONDUCTIVE EPOXY: FILL_0.250 9.84 MIL</td>
</tr>
</tbody>
</table>

**ADDITIONAL REQUIREMENTS:**
- **VENDOR DATE CODE, UL, LOGO:**
- **THICKNESS:**
- **VENDOR MARKING:**
- **ADDITIONAL REQUIREMENTS:**
- **BOARD SURFACE TREATMENT:**
  - **SILKSCREEN COLOR:**
  - **SOLDERMASK COLOR:** (PER IPC-6011,6012)

**SPECIAL FAB NOTES:**
- FABRICATION SHOP MUST FOLLOW THE SOLDER MASK REVIEW LAYERS.
- PLACE DRAWING HERE:

**CUSTOMER INFORMATION:**
- **BOARD NAME:**
- **ENGINEER:**
- **PART NUMBER:**
- **FABRICATION DRAWING:**
- **REV.:**
- **DATE:**
- **JOB NO.:**
- **KSID NO.:**
- **JOB NUMBER:**
- **KSID:**
- **VENDOR DATE CODE, UL, LOGO:**
- **THROUGH-HOLE VIA TREATMENT:**
  - **CORE_1.00 35.12 MIL**
  - **FILL_0.250 9.84 MIL**

**REFERENCE:**
- **NUMBER OF LAYERS:**
- **MIN. TRACK WIDTH:**
- **MIN. CLEARANCE:**
- **MIN. VIA PAD/DRILL:**
- **MIN. ANNULAR 2 MIL EXTERNAL PER IPC-6012C CLASS 2**
- **REGISTRATION TOLERANCES:**
  - **METAL +/- X MIL**
  - **HOLES +/- X MIL**

**TOLERANCES:**
- **50 +/- 10%**
- **0.050 +/-0.001**
- **0.050 +/-0.001**
- **0.050 +/-0.001**

**DESCRIPTION INFORMATION:**
- **THICKNESS:**
  - **FR-4 HIGH Tg:** 0.062" +/-10%
  - **ROGERS 4350B:** 0.093" +/-10%
  - **IPC-6012C TYPE 3 CLASS 2**
- **LAMINATE MATERIAL:**
  - **ROGERS 4350B**
  - **FR-4 HIGH Tg**

**SPECIAL FAB NOTES:**
- **PLACE DRAWING HERE:**
- **WIRE BONDING:**
- **SOLDERMASK REVIEW LAYERS:**
- **THROUGH-HOLE VIA TREATMENT:**
- **VIA FILL USING NON-CONDUCTIVE EPOXY:**
- **VENDOR DATE CODE, UL, LOGO:**
- **THICKNESS:**
- **VENDOR MARKING:**
- **ADDITIONAL REQUIREMENTS:**
- **BOARD SURFACE TREATMENT:**
  - **SILKSCREEN COLOR:**
  - **SOLDERMASK COLOR:** (PER IPC-6011,6012)

**SPECIAL FAB NOTES:**
- **PLACE DRAWING HERE:**
- **WIRE BONDING:**
- **SOLDERMASK REVIEW LAYERS:**
- **THROUGH-HOLE VIA TREATMENT:**
- **VIA FILL USING NON-CONDUCTIVE EPOXY:**
- **VENDOR DATE CODE, UL, LOGO:**
- **THICKNESS:**
- **VENDOR MARKING:**
- **ADDITIONAL REQUIREMENTS:**
- **BOARD SURFACE TREATMENT:**
  - **SILKSCREEN COLOR:**
  - **SOLDERMASK COLOR:** (PER IPC-6011,6012)
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